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MARKING

# TinyLogic UHS Dual 2-Input NAND Gate (Open Drain Output)

# NC7WZ38

#### Description

The NC7WZ38 is a dual 2–Input NAND Gate with open drain output stage from ON Semiconductor's Ultra High Speed Series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a very broad V<sub>CC</sub> operating range. The device is specified to operate over the 1.65 V to 5.5 V V<sub>CC</sub> range. The inputs and output are high impedance when V<sub>CC</sub> is 0 V. Inputs tolerate voltages up to 5.5 V independent of V<sub>CC</sub> operating voltage. The open drain output stage will tolerate voltages up to 5.5 V independent of V<sub>CC</sub> when in the high impedance state.

#### Features

- Space Saving US8 Surface Mount Package
- MicroPak<sup>™</sup> Pb-Free Leadless Package
- Open Drain Output Stage for OR Tied Applications
- Ultra High Speed: t<sub>PD</sub> 2.2 ns Typ. into 50 pF at 5 V V<sub>CC</sub>
- High Output Sink Drive: ±24 mA at 3 V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range: 1.65 V to 5.5 V
- Matches the Performance of LCX when Operated at 3.3 V  $V_{CC}$
- Power Down High Impedance Inputs / Output
- Overvoltage Tolerant Inputs Facilitate 5 V to 3 V Translation
- Patented Noise / EMI Reduction Circuitry Implemented
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

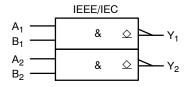
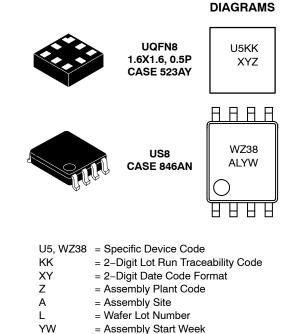


Figure 1. Logic Symbol



#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

#### **Connection Diagram**

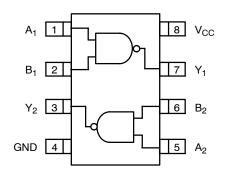
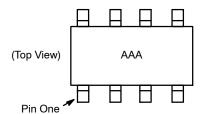


Figure 2. Connection Diagram (Top View)



AAA represents Product Code Top Mark - see ordering code

NOTE: Orientation of Top Mark determines Pin One location. Read the top product code mark left to right, Pin One is the lower left pin (see diagram).

#### Figure 3. Pin One Orientation Diagram

#### **PIN DESCRIPTIONS**

Pin Names	Description
A <sub>n</sub> , B <sub>n</sub>	Inputs
Y <sub>n</sub>	Output

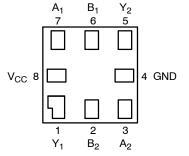


Figure 4. Pad Assignments for MicroPak (Top Thru View)

<b>FUNCTION TABLE</b> $(Y = \overline{AB})$
---------------------------------------------

Inp	Output	
А	В	Y
L	L	*H
L	Н	*H
Н	L	*H
Н	Н	L

H = HIGH Logic Level

L = LOW Logic Level

\*H = HIGH Impedance Output State (Open Drain)

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage	-0.5	6.5	V
V <sub>IN</sub>	DC Input Voltage	-0.5	6.5	V
V <sub>OUT</sub>	DC Output Voltage	-0.5	6.5	V
I <sub>IK</sub>	DC Input Diode Current V <sub>IN</sub> < 0 V	-	-50	mA
I <sub>OK</sub>	DC Output Diode Current V <sub>OUT</sub> < 0 V	-	-50	mA
I <sub>OUT</sub>	DC Output Current	-	±50	mA
$I_{CC} / I_{GND}$	DC V <sub>CC</sub> / GND Current	-	±100	mA
T <sub>STG</sub>	Storage Temperature	-65	+150	°C
TJ	Junction Temperature under Bias	-	150	°C
ΤL	Junction Lead Temperature (Soldering, 10 Seconds)	-	260	°C
PD	Power Dissipation in Still Air MicroP	US8 – /ak-8 –	500 539	mW

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol		Parameter	Min	Мах	Unit
V <sub>CC</sub>	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Rete	ntion	1.5	5.5	
V <sub>IN</sub>	Input Voltage		0	5.5	V
V <sub>OUT</sub>	Output Voltage		0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time $V_{CC}$ = 1.8 V ±0.15 V, 2.5 V ±0.2 V		0	20	ns/V
		$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0	10	
	$V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$		0	5	
$\theta_{JA}$	Thermal Resistance	US8 MicroPak–8		250 232	°C/W

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability. 1. Unused inputs must be held HIGH or LOW. They may not float.

## DC ELECTICAL CHARACTERISTICS

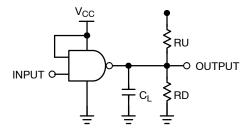
					Т,	a = +25°	°C	T <sub>A</sub> = -40	to +85°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Co	onditions	Min	Тур	Max	Min	Max	Unit
VIH	HIGH Level Input	1.65 to 1.95			0.65 V <sub>CC</sub>	-	-	0.65 V <sub>CC</sub>	-	V
	Voltage	2.3 to 5.5			$0.7  V_{CC}$	-	-	0.7 V <sub>CC</sub>	-	
V <sub>IL</sub>	LOW Level Input	1.65 to 1.95			-	-	0.35 V <sub>CC</sub>	-	0.35 V <sub>CC</sub>	V
	Voltage	2.3 to 5.5			-	Ì	0.3 V <sub>CC</sub>	-	0.3 V <sub>CC</sub>	
I <sub>LKG</sub>	HIGH Level Output Leakage	5.5	V <sub>IN</sub> = V <sub>IL</sub> V <sub>OUT</sub> = V <sub>C</sub>	<sub>CC</sub> or GND	-	-	±5	-	±10	μΑ
V <sub>OL</sub>		1.65	$V_{IN} = V_{IH}$	I <sub>OL</sub> = 100 μA	-	0.0	0.1	-	0.1	V
Voltage	2.3			-	0.0	0.1	-	0.1		
		3.0			-	0.0	0.1	-	0.1	
		4.5			-	0.0	0.1	-	0.1	
		1.65		I <sub>OL</sub> = 4 mA	-	0.08	0.24	-	0.24	
		2.3		I <sub>OL</sub> = 8 mA	-	0.10	0.3	_	0.3	
		3.0		I <sub>OL</sub> = 16 mA	-	0.15	0.4	-	0.4	
		3.0		I <sub>OL</sub> = 24 mA	-	0.22	0.55	-	0.55	
		4.5		I <sub>OL</sub> = 32 mA	-	0.22	0.55	-	0.55	
I <sub>IN</sub>	Input Leakage Current	5.5	V <sub>IN</sub> = 5.5 V, GND		-	-	±0.1	-	±1	μA
I <sub>OFF</sub>	Power Off Leakage Current	0.0	$V_{IN}$ or $V_{OUT}$ = 5.5 V		-	-	1	-	10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	1.65 to 5.5	V <sub>IN</sub> = 5.5 \	/, GND	-	I	1	-	10	μΑ

### AC ELECTRICAL CHARACTERISTICS

				$T_A = +25^{\circ}C$ $T_A = -40 t$			to +85°C		
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t <sub>PZL</sub>	Propagation Delay	1.8 ±0.15	$C_{L} = 50 \text{ pF},$	-	5.2	9.2	-	9.6	ns
	(Figure 5, 7)	2.5 ±0.2	RU = 500 Ω, RD = 500 Ω,	-	3.5	5.7	-	6.1	
		3.3 ±0.3	$V_{I} = 2 \times V_{CC}$	-	2.8	4.1	-	4.5	
		5.0 ±0.5		-	2.2	3.4	-	3.6	
t <sub>PLZ</sub>	t <sub>PLZ</sub> Propagation Delay (Figure 5, 7)	1.8 ±0.15	$\begin{array}{l} C_{L} = 50 \ \text{pF}, \\ \text{RU} = 500 \ \Omega, \\ \text{RD} = 500 \ \Omega, \\ \text{V}_{\text{I}} = 2 \ \text{x} \ \text{V}_{\text{CC}} \end{array}$	-	4.6	9.2	-	9.6	ns
		2.5 ±0.2		-	3.2	5.7	-	6.1	
		3.3 ±0.3		-	2.4	4.1	-	4.5	
		5.0 ±0.5		-	1.6	3.4	-	3.6	
C <sub>IN</sub>	Input Capacitance	0		-	2.5	-	-	-	pF
C <sub>OUT</sub>	Output Capacitance	0		-	4.2	-	-	-	pF
C <sub>PD</sub>	Power Dissipation Capacitance	3.3	(Note 2)	-	7	-	-	-	pF
	(Figure 6)	5.0		-	9	-	-	-	1

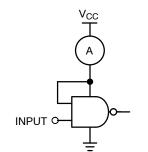
2.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle. (see Figure 6)  $C_{PD}$  is related to I<sub>CCD</sub> dynamic operating current by the expression: I<sub>CCD</sub> = ( $C_{PD}$ ) (V<sub>CC</sub>) ( $f_{IN}$ ) + (I<sub>CC</sub>static).

#### AC Loading and Waveforms



 $C_L$  includes load and stray capacitance Input PRR = 1.0 MHz,  $t_W$  = 500 ns

#### Figure 5. AC Test Circuit



Input = AC Waveform;  $t_r = t_f = 1.8$  ns; PRR = 10 MHz; Duty Cycle = 50%.

#### Figure 6. I<sub>CCD</sub> Test Circuit

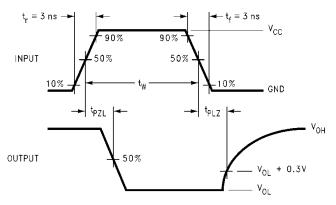


Figure 7. AC Waveforms

#### **ORDERING INFORMATION**

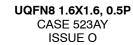
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NC7WZ38K8X	WZ38	8-Lead US8, JEDEC MO-187, Variation CA	3000 / Tape & Reel
NC7WZ38K8X-L22236	WZ38	3.1 mm Wide	3000 / Tape & Reel
NC7WZ38L8X	U5	8-Lead MicroPak, 1.6 mm Wide	5000 / Tape & Reel
NC7WZ38L8X-L22185	U5	(Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

3. Pb-Free package per JEDEC J-STD-020B.

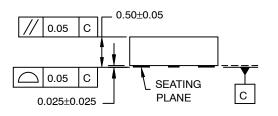
MicroPak is trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.



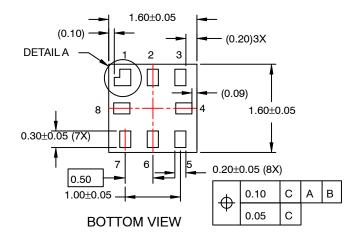


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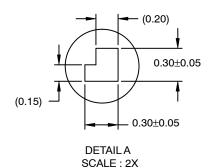
SIDE VIEW





NOTES:

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- B. DIMENSIONS ARE IN MILLIMETERS.
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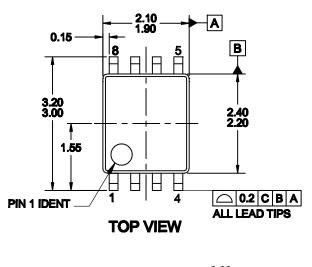
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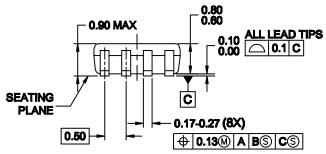
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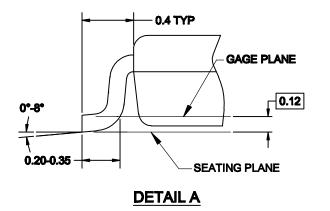
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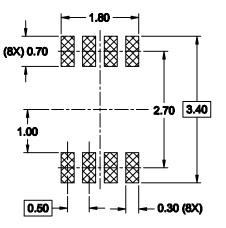
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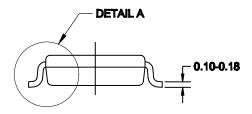




## **RECOMMENDED LAND PATTERN**

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